



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : LEE et al. Confirmation No: 4969  
Appl. No. : 10/664,981  
Filed : September 22, 2003  
Title : SEMICONDUCTOR PACKAGE WITH THERMAL  
ENHANCE FILM AND MANUFACTURING METHOD  
THEREOF

TC/A.U. : 2815  
Examiner : C.C. Chu

Docket No.: LEEC3073/REF  
Customer No: 23364

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of June 16, 2004, in connection with the above-identified application. This response is timely filed.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.